	บ	Document ID	Title	Current OR
1	Ø	US 4921815 A	Method of producing a semiconductor memory device having trench capacitors	438/248
2	⊠	US 5153685 A	Semiconductor integrated circuit device having switching MISFET and capacitor element and method of producing the same, including wiring therefor and method of producing such wiring	257/296
3	×	US 5753550 A	Semiconductor integrated circuit device having switching MISFET and capacitor element and method of producing the same, including wiring therefor and method of producing such wiring	438/253
4	Ø	US 5792693 A	Method for producing capacitors having increased surface area for dynamic random access memory	438/254
5		US 5930624 A	Method of producing semiconductor integrated circuit device having switching MISFET and capacitor element including wiring	438/253
6		US 6281071 B1	Method of producing semiconductor integrated circuit device having switching MISFET and capacitor element including wiring therefor and method of producing such wiring	438/253
7		US 20020028574 A1	Semiconductor integrated circuit device having switching misfet and capacitor element and method of producing the same, including wiring therefor and method of producing such wiring	438/618

L Number	Hits	Search Text	DB	Time stamp
1	5	"capacitive electrode" near5 "semiconductor substrate"	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/03/11 10:37
2	12	"capacitive electrode" with "semiconductor substrate"	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/11 10:38
6	2	("capacitive electrode" with "semiconductor substrate") and "metal" and (oxidation or oxide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/11 10:45
7	15	("4367580" "4682402" "5185689" "5356826" "5500387" "5585303" "5591658" "5614431" "5618749" "5683931" "5716863" "5759887" "5792683" "5885862" "5970338").PN.	USPAT	2002/03/11 10:44
8	72983	method adj produc\$.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/11 11:08
9	14	(method adj produc\$.ti.) adj oxidation.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/11 11:08
14	351	(method adj produc\$.ti.) and (capacitor or capacitive).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/11 11:10
18	30	((method adj produc\$.ti.) and (capacitor or capacitive).ti.) and electrode.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/11 11:12
21	176	"capacitive electrode".ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/11 11:12
23	11	"capacitive electrode".ti. and method.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/11 11:13
24	46	<pre>((method adj produc\$.ti.) and (capacitor or capacitive).ti.) and "semiconductor substrate"</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/11
25	21	(((method adj produc\$.ti.) and (capacitor or capacitive).ti.) and "semiconductor substrate") and metal and oxide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/11 11:14
26	11	((((method adj produc\$.ti.) and (capacitor or capacitive).ti.) and "semiconductor substrate") and metal and oxide) and oxidation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/11

27	10	((((method adj produc\$.ti.) and	USPAT;	2002/03/11
- '	10	(capacitor or capacitive).ti.) and	US-PGPUB;	11:15
		"semiconductor substrate") and metal and	EPO; JPO;	
		oxide) and oxidation) and (inhibiti or	DERWENT;	
		inhibiting or "slow down" or reduce or	IBM TDB	
		hamper)	<u>-</u>	
28	10		USPAT;	2002/03/11
		(capacitor or capacitive).ti.) and	US-PGPUB;	11:16
		"semiconductor substrate") and metal and	EPO; JPO;	
		oxide) and oxidation) and (inhibiti or	DERWENT;	
		inhibiting or "slow down" or reduce or	IBM TDB	
		hamper)) and layer	_	
29	8		USPAT;	2002/03/11
		(capacitor or capacitive).ti.) and	US-PGPUB;	11:16
		"semiconductor substrate") and metal and	EPO; JPO;	
		oxide) and oxidation) and (inhibiti or	DERWENT;	
		inhibiting or "slow down" or reduce or	IBM_TDB	
İ		hamper)) and layer) and electrically		
30	7	(((((((method adj produc\$.ti.) and	USPAT;	2002/03/11
		(capacitor or capacitive).ti.) and	US-PGPUB;	11:17
		"semiconductor substrate") and metal and	EPO; JPO;	
		oxide) and oxidation) and (inhibiti or	DERWENT;	
		inhibiting or "slow down" or reduce or	IBM_TDB	
		hamper)) and layer) and electrically) and		
L		(conductive or conductor)		